

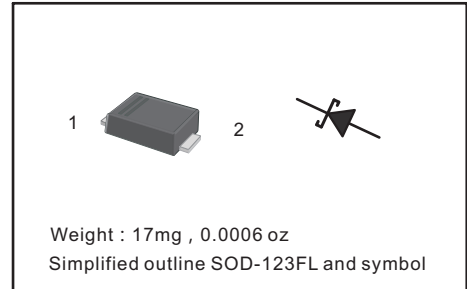
## SCHOTTKY BARRIER RECTIFIERS

### Features

- Metal silicon junction, majority carrier conduction
- Guarding for overvoltage protection
- Low power loss, high efficiency
- High current capability
- low forward voltage drop
- High surge capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



### Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Parameter	Symbols	B5817WL	B5818WL	B5819WL	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	30	40	V
Maximum RMS voltage	$V_{RMS}$	14	21	28	V
Maximum DC Blocking Voltage	$V_{DC}$	20	30	40	V
Maximum Average Forward Rectified Current 0.375" (9.5 mm) Lead Length at $T_L = 90^\circ\text{C}$	$I_{F(AV)}$	1			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method) at $T_L = 70^\circ\text{C}$	$I_{FSM}$	25			A
Maximum Instantaneous Forward Voltage at 1 A Maximum Instantaneous Forward Voltage at 3.1 A	$V_F$	0.45 0.75	0.55 0.875	0.6 0.9	V
Maximum Instantaneous Reverse Current at $T_A = 25^\circ\text{C}$ Rated DC Reverse Voltage $T_A = 100^\circ\text{C}$	$I_R$	1 10			mA
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JL}$	50 15			$^\circ\text{C}/\text{W}$
Typical Junction Capacitance	$C_j$	110			pF
Storage and Operating Junction Temperature Range	$T_j, T_{stg}$	-55 ~ +125			$^\circ\text{C}$

Fig.1 Forward Current Derating Curve

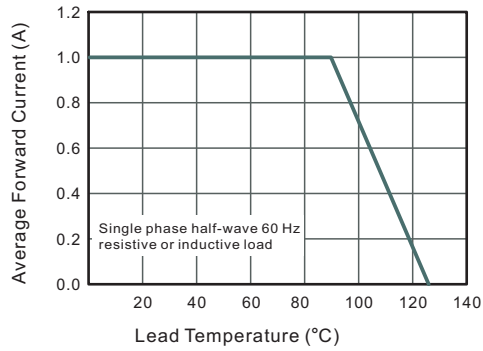


Fig.2 Typical Reverse Characteristics

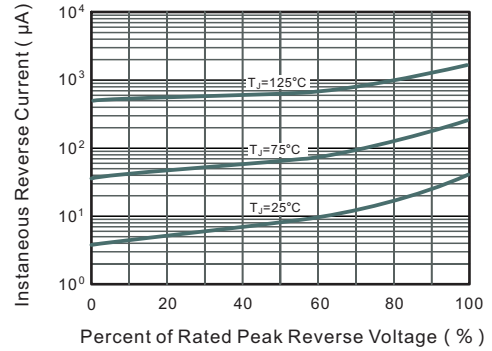


Fig.3 Typical Forward Characteristic

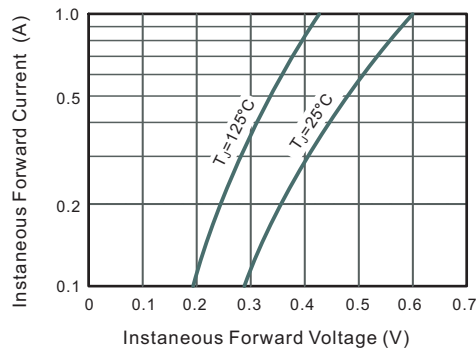


Fig.4 Typical Junction Capacitance

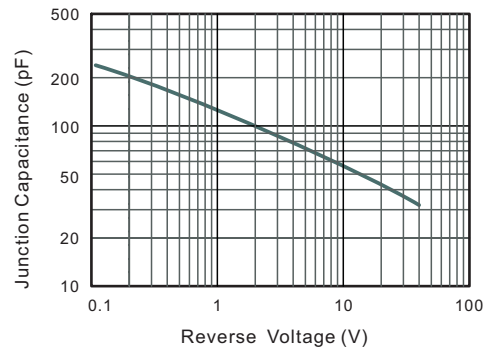


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

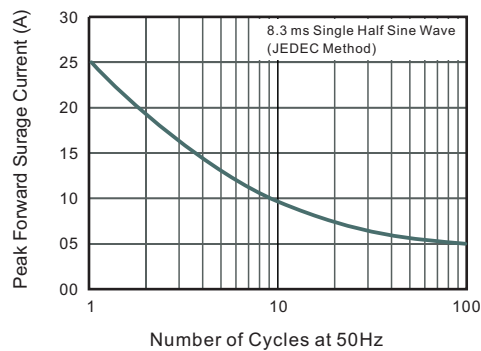
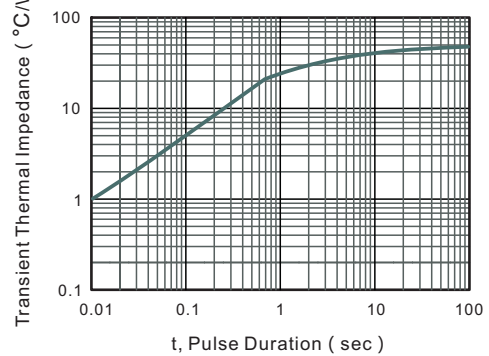


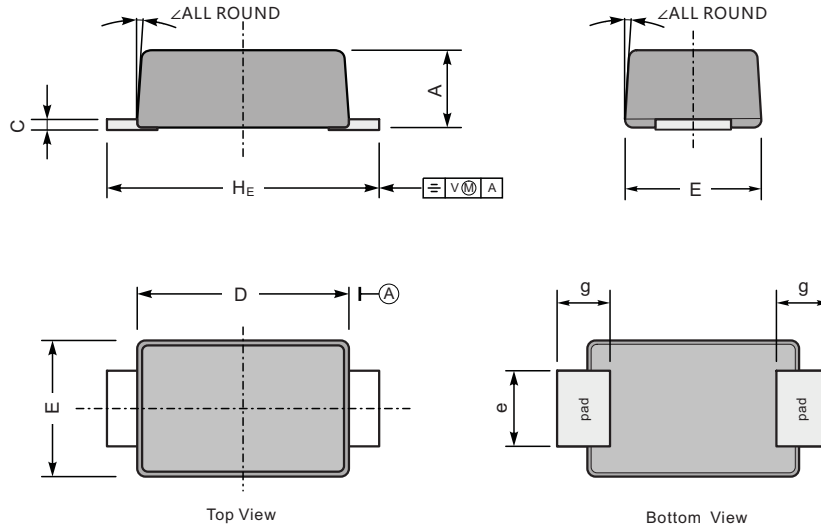
Fig.6- Typical Transient Thermal Impedance



## PACKAGE OUTLINE

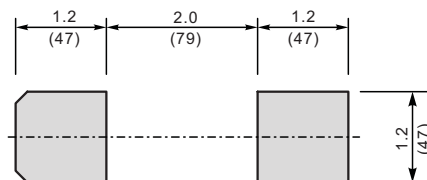
Plastic surface mounted package; 2 leads

SOD123FL



UNIT		A	C	D	E	e	g	H <sub>E</sub>	$\angle$
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

### The recommended mounting pad size

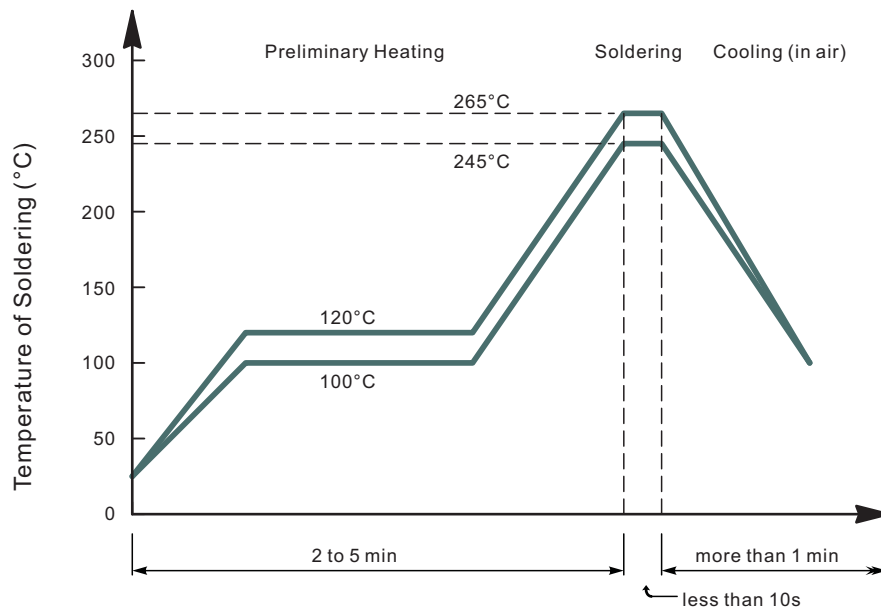


Unit:  $\frac{\text{mm}}{\text{mil}}$

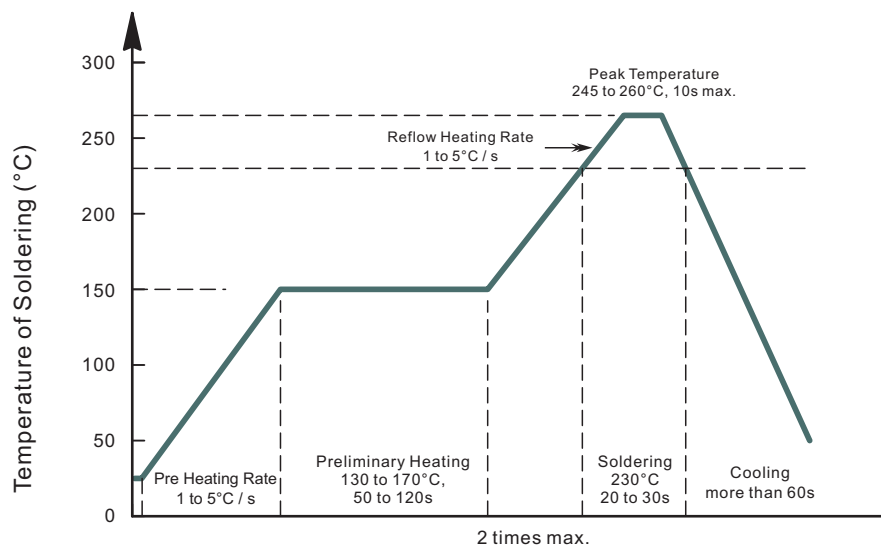
### Marking

Type number	Marking code
B5817WL	SJ
B5818WL	SK
B5819WL	SL

## Recommended condition of flow soldering



## Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

### • Condition of hand soldering

Temperature: 320°C

Time: 3s max.

Times: one time

### • Remark:

Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)

单击下面可查看定价，库存，交付和生命周期等信息

[>>SHIKUES\(时科\)](#)